

N-Channel 100-V (D-S) 175 °C MOSFET

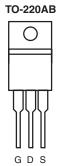
| PRODUCT SUMMARY | | | | |
|--|--------|--|--|--|
| V _{DS} (V) | 100 | | | |
| $R_{DS(on)} (\Omega)$ at $V_{GS} = 10 V$ | 0. 009 | | | |
| $R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 V$ | 0. 020 | | | |
| I _D (A) | 100 | | | |
| Configuration | Single | | | |

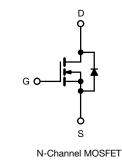
FEATURES

• TrenchFET[®] Power MOSFET



175 °C Maximum Junction Temperature
Compliant to RoHS Directive 2002/95/EC





| ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted | | | | | |
|---|--|-----------------|------------------|------|--|
| Parameter | | | Limit | Unit | |
| Drain-Source Voltage | V _{DS} | 100 | V | | |
| Gate-Source Voltage | | | ± 20 | v | |
| Continuous Drain Current (T _J = 150 °C) | T _C = 25 °C | I _D | 100 | | |
| | T _C = 125 °C | U | 75 ^a | А | |
| Pulsed Drain Current | I _{DM} | 300 | A | | |
| Avalanche Current | L = 0.1 mH | | 75 | | |
| Single Pulse Avalanche Energy ^b | L = 0.1 mm | E _{AS} | 280 | mJ | |
| Menimum Denner Dissignation ^b | T_{C} = 25 °C (TO-220AB and TO-263) | PD | 250 ^c | W | |
| Maximum Power Dissipation ^b | T _A = 25 °C (TO-263) ^d | ۰D | 3.75 | vv | |
| Operating Junction and Storage Temperat | T _J , T _{stg} | - 55 to 175 | °C | | |

| THERMAL RESISTANCE RATINGS | | | | | | |
|----------------------------|---------------------------------|-------------------|-------|------|--|--|
| Parameter | | Symbol | Limit | Unit | | |
| Junction-to-Ambient | PCB Mount (TO-263) ^d | R _{thJA} | 40 | | | |
| | Free Air (TO-220AB) | | 62.5 | °C/W | | |
| Junction-to-Case | | R _{thJC} | 0.6 | | | |

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

| 5 | 3 | ® | Bs | semi | Ĺ |
|---|------|-----|-----|--------|---|
| W | vw.\ | /B: | sen | ni.com | 1 |

| Parameter | Symbol | Test Conditions | Min. | Тур. | Max. | Unit | |
|---|--|---|------|-------|-------|------|--|
| Static | | · | | | | | |
| Drain-Source Breakdown Voltage | V_{DS} $V_{GS} = 0 V, I_D = 250 \mu A$ | | 100 | | | V | |
| Gate-Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$ | 2 | | 4 | V | |
| Gate-Body Leakage | I _{GSS} | $V_{DS} = 0 V, V_{GS} = \pm 20 V$ | | | ± 100 | nA | |
| | | $V_{DS} = 100 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$ | | | 1 | | |
| Zero Gate Voltage Drain Current | I _{DSS} | $V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$ | | | 50 | μA | |
| | | $V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 175 ^{\circ}\text{C}$ | | | 250 | 1 | |
| On-State Drain Current ^a | I _{D(on)} | $V_{DS} = \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$ | 120 | | | А | |
| | | V _{GS} = 10 V, I _D = 30 A | | 0.009 | | | |
| | P | $V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 20 \text{ A}$ | | 0.020 | | Ω | |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | $V_{GS} = 10 \text{ V}, \text{ I}_{D} = 30 \text{ A}, \text{ T}_{J} = 125 ^{\circ}\text{C}$ | | 0.023 | | | |
| | | $V_{GS} = 10 \text{ V}, \text{ I}_{D} = 30 \text{ A}, \text{ T}_{J} = 175 ^{\circ}\text{C}$ | | 0.030 | | | |
| Forward Transconductance ^a | 9 _{fs} | V _{DS} = 15 V, I _D = 30 A | 25 | | | S | |
| Dynamic ^b | | · | | • | | | |
| Input Capacitance | C _{iss} | | | 4700 | | pF | |
| Output Capacitance | C _{oss} | $V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz$ | | 665 | | | |
| Reverse Transfer Capacitance | C _{rss} | | | 265 | | | |
| Total Gate Charge ^c | Qg | | | 105 | 160 | | |
| Gate-Source Charge ^c | Q _{gs} | $V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 85 \text{ A}$ | | 17 | | nC | |
| Gate-Drain Charge ^c | Q _{gd} | | | 23 | | | |
| Turn-On Delay Time ^c | t _{d(on)} | | | 12 | 25 | | |
| Rise Time ^c | t _r | V_{DD} = 50 V, R_L = 0.6 Ω | | 90 | 135 | - | |
| Turn-Off DelayTime ^c | t _{d(off)} | $\text{I}_\text{D}\cong\text{85}$ A, V_GEN = 10 V, R_g = 2.5 Ω | | 55 | 85 | ns | |
| Fall Time ^c | t _f | | | 130 | 195 | | |
| Source-Drain Diode Ratings and Cha | racteristics T _C | = 25 °C ^b | | | | | |
| Continuous Current | ۱ _S | | | | 85 | ٨ | |
| Pulsed Current | I _{SM} | | | | 240 | A | |
| Forward Voltage ^a | V _{SD} | I _F = 85 A, V _{GS} = 0 V | | 1.0 | 1.5 | V | |
| Reverse Recovery Time | t _{rr} | | | 85 | 140 | ns | |
| Peak Reverse Recovery Current | I _{RM(REC)} | I _F = 50 A, dI/dt = 100 A/μs | | 4.5 | 7 | А | |
| Reverse Recovery Charge | Q _{rr} | 1 | | 0.17 | 0.35 | μC | |

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

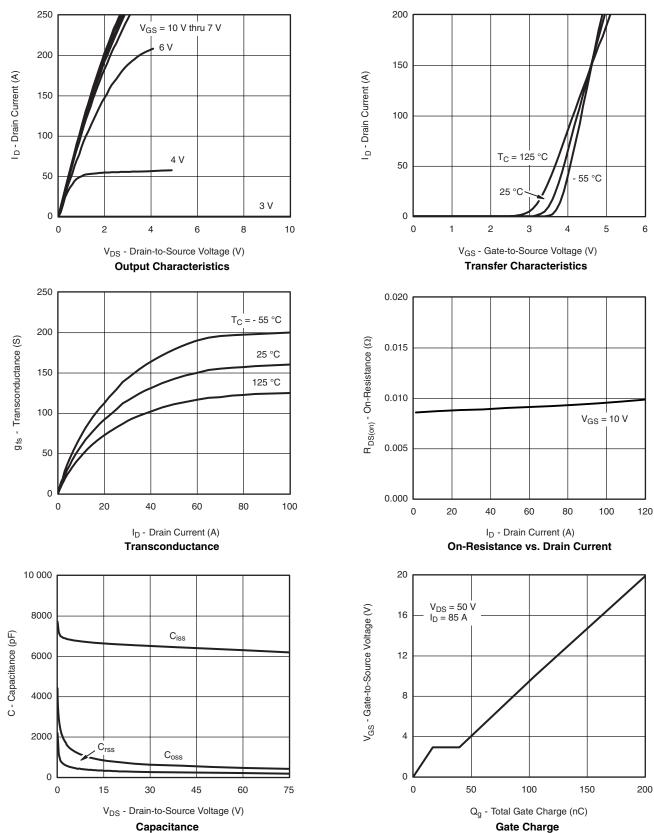
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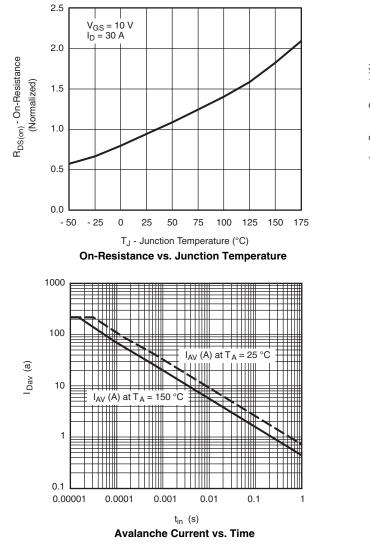


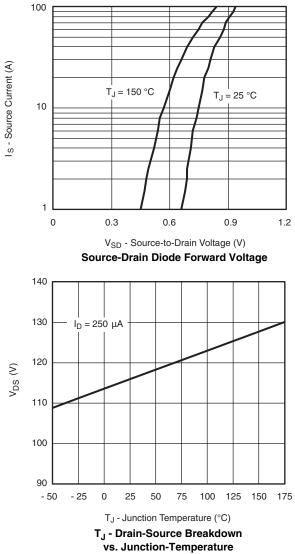
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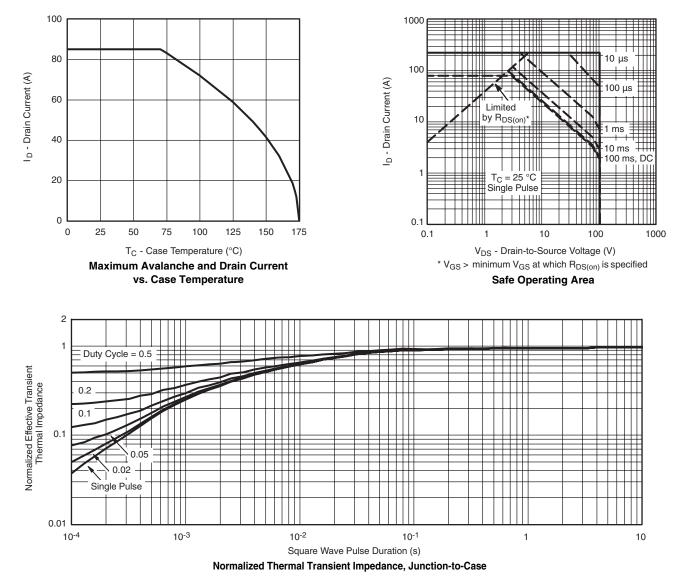
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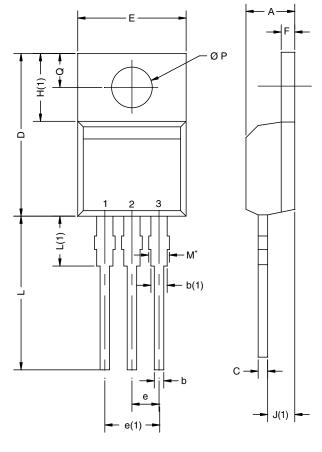


THERMAL RATINGS





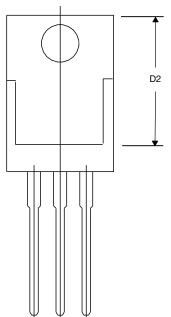
TO-220AB



| | MILLIMETERS | | INC | HES |
|--|-------------|-------|-------|-------|
| DIM. | MIN. | MAX. | MIN. | MAX. |
| А | 4.25 | 4.65 | 0.167 | 0.183 |
| b | 0.69 | 1.01 | 0.027 | 0.040 |
| b(1) | 1.20 | 1.73 | 0.047 | 0.068 |
| С | 0.36 | 0.61 | 0.014 | 0.024 |
| D | 14.85 | 15.49 | 0.585 | 0.610 |
| D2 | 12.19 | 12.70 | 0.480 | 0.500 |
| E | 10.04 | 10.51 | 0.395 | 0.414 |
| е | 2.41 | 2.67 | 0.095 | 0.105 |
| e(1) | 4.88 | 5.28 | 0.192 | 0.208 |
| F | 1.14 | 1.40 | 0.045 | 0.055 |
| H(1) | 6.09 | 6.48 | 0.240 | 0.255 |
| J(1) | 2.41 | 2.92 | 0.095 | 0.115 |
| L | 13.35 | 14.02 | 0.526 | 0.552 |
| L(1) | 3.32 | 3.82 | 0.131 | 0.150 |
| ØР | 3.54 | 3.94 | 0.139 | 0.155 |
| Q | 2.60 | 3.00 | 0.102 | 0.118 |
| ECN: T14-0413-Rev. P, 16-Jun-14 DWG: 5471 | | | | |

Note

* M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM





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